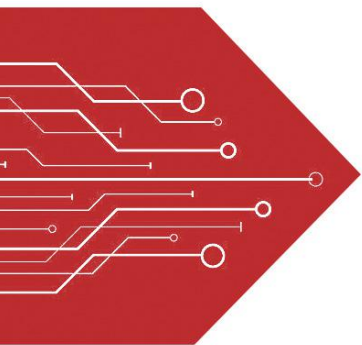


MSKSEMI

SEMICONDUCTOR



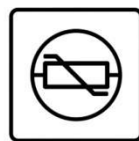
ESD



TVS



TSS



MOV



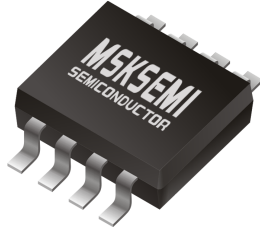
GDT



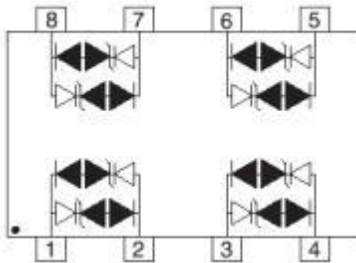
PLED

Product data sheet

www.msksemi.com



SOP-8



Features

- 400 W Peak Pulse Power per Line ($t_p=8/20\mu s$)
- Protects four line pairs
- Low capacitance
- Low Leakage Current.
- Low Operating and Clamping Voltages.
- Transient Protection for High Speed Data Lines to
IEC61000-4-2(ESD) $\pm 15kV$ (air), $\pm 8kV$ (Contact)
IEC61000-4-4(EFT) 40A(5/50ns)
IEC61000-4-5(lightning) 24A(8/20us)

Applications

- Ethernet – 10/100/1000 Base T
- WAN/LAN Equipment
- Desktops, Servers, Notebooks & Handhelds, base stations Laser Diode Protection

Absolute Maximum Ratings

Parameter	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$) - See Fig1.	P_{PK}	400	W
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	24	A
Storage Temperature Range	T_{STG}	-55 to 150	$^{\circ}C$
Operating Junction Temperature Range	T_J	-55 to 150	$^{\circ}C$

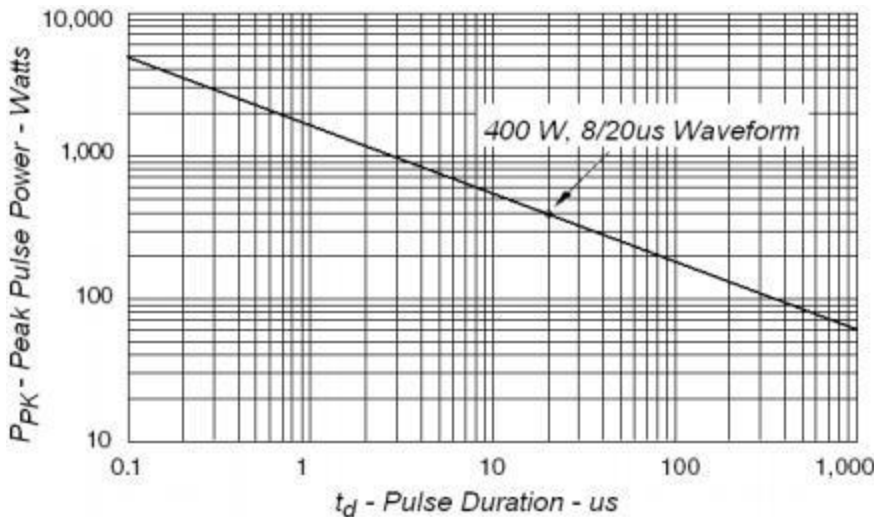


Fig1. Peak Pulse Power VS Pulse Time

Electrical Parameter

Symbol	Parameter
I_{PP}	Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{SB}	Snap-Back Voltage @ I_{SB}
I_{SB}	Snap-Back Current
V_{PT}	Punch-Through Voltage
I_{PT}	Punch-Through Current

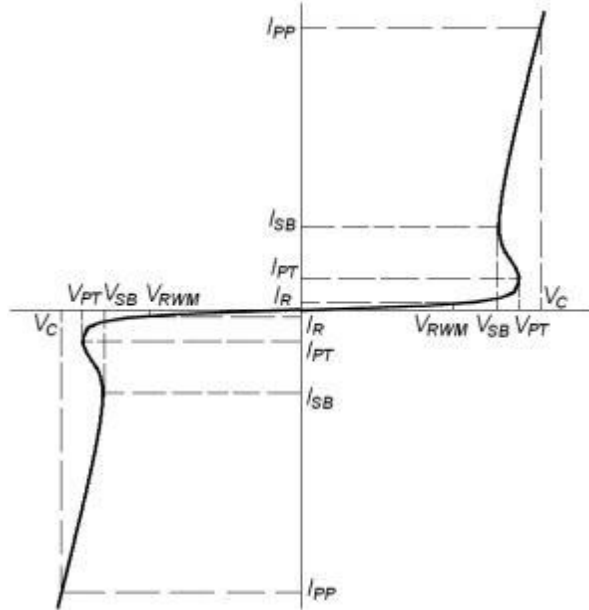


Fig2. SLVU2.8-8 IV Characteristic Curve

Electrical Characteristics

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				2.8	V
Punch-Through Voltage	V_{PT}	$I_{PT} = 2\mu A$	3.0			V
Snap-Back Voltage	V_{SB}	$I_{SB} = 50mA$	2.8			V
Reverse Leakage Current	I_R	$V_{RWM} = 2.8V, T = 25^\circ C$ (Each Line)			1	μA
Clamping Voltage	V_C	$I_{PP} = 2A, t_p = 8/20\mu s$ (Each Line)			5.5	V
Clamping Voltage	V_C	$I_{PP} = 5A, t_p = 8/20\mu s$ (Each Line)			8.5	V
Clamping Voltage	V_C	$I_{PP} = 24A, t_p = 8/20\mu s$ (Each Line)			15	V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$ (Each Line)		7	10	pF

Typical Characteristics

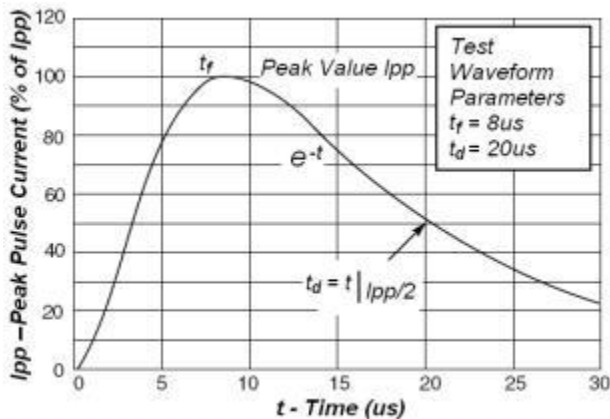


Fig3. Pulse Waveform

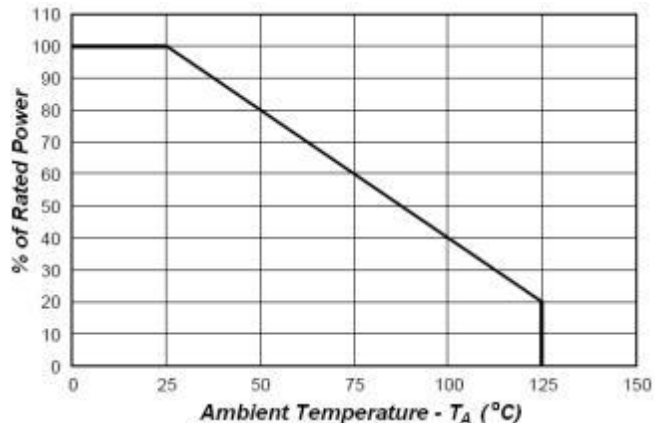
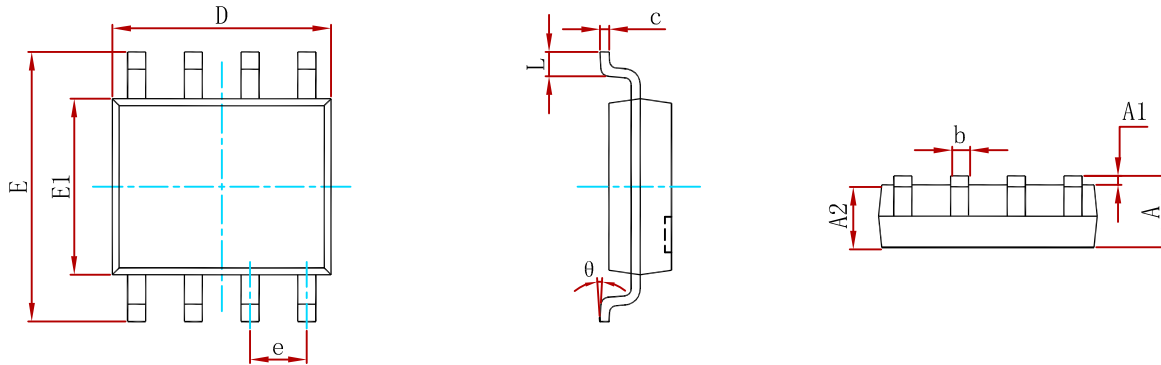


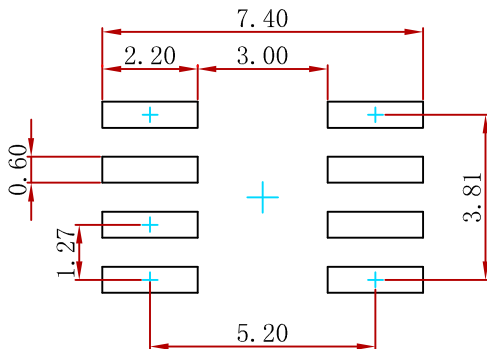
Fig4. Power Derating Curve

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SLVU2.8-8-MS	SOP-8	2500

Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringement of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.

单击下面可查看定价，库存，交付和生命周期等信息

[>>MSKSEMI\(美森科\)](#)